

OK TO ENTER: /EL/

Docket No.: 0033-1048PUS1  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Shinji TAKASE et al.

Application No.: 10/562,356

Confirmation No.: 6294

Filed: December 27, 2005

Art Unit: 1791

For: METHOD OF RESIN SEALING OF  
ELECTRONIC COMPONENT AND MOLD  
USED IN THE METHOD

Examiner: E. H. Lee

**AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Madam:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated April 6, 2009, finally rejecting claims 1-2, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 3 of this paper.